T-1 3/4 (5mm) BI-LEVEL LED INDICATOR

Part Number: WP1503EB/2SRD Super Bright Red

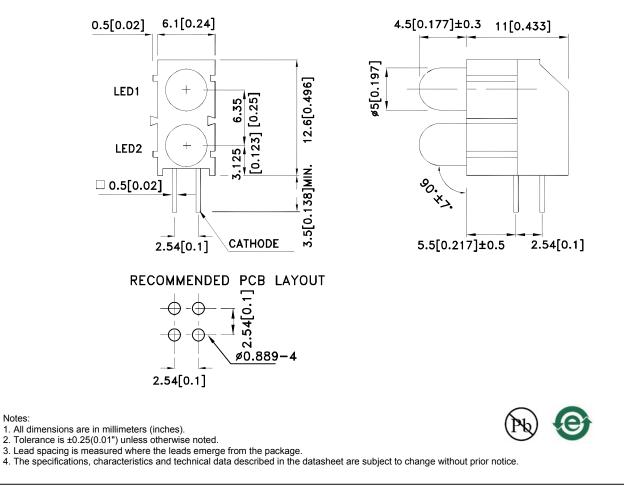
Features

- Pre-trimmed leads for pc board mounting.
- Stackable units.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



Notes:

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Selection Guide

Part No.	Dice	Dice Lens Type @ 20mA		Viewing Angle [1]	
			Min.	Тур.	201/2
WP1503EB/2SRD	Super Bright Red (GaAlAs)	Red Diffused	500	1000	60°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Red		10	uA	VR = 5V

Notes:

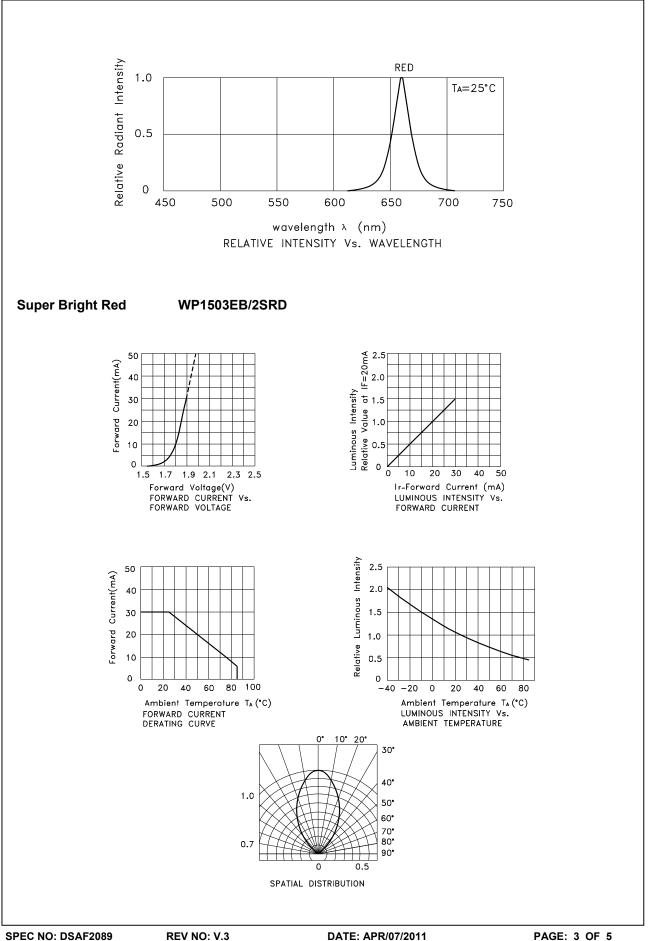
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

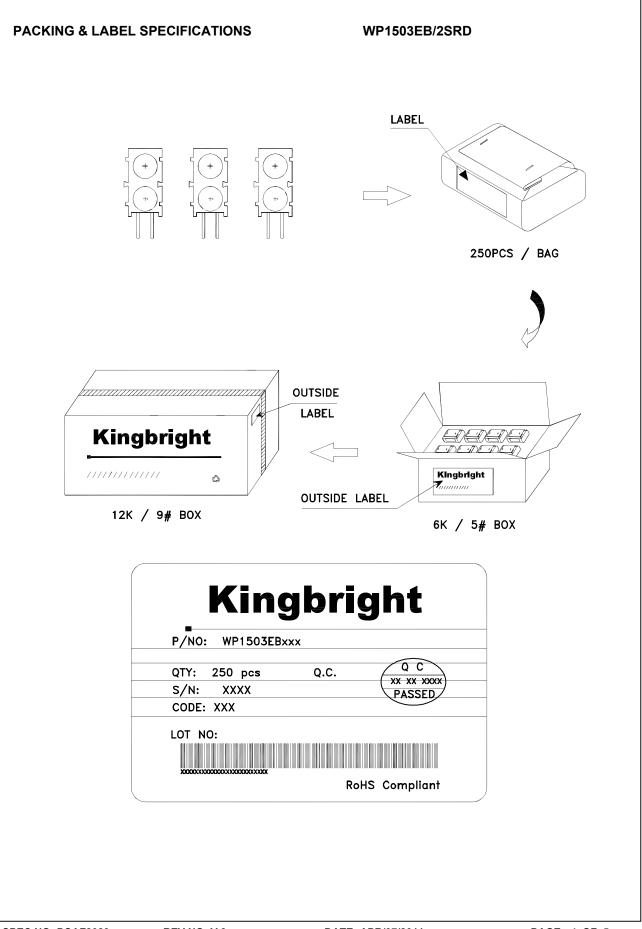
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Red	Units	
Power dissipation	75	mW	
DC Forward Current	30		
Peak Forward Current [1]	155	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

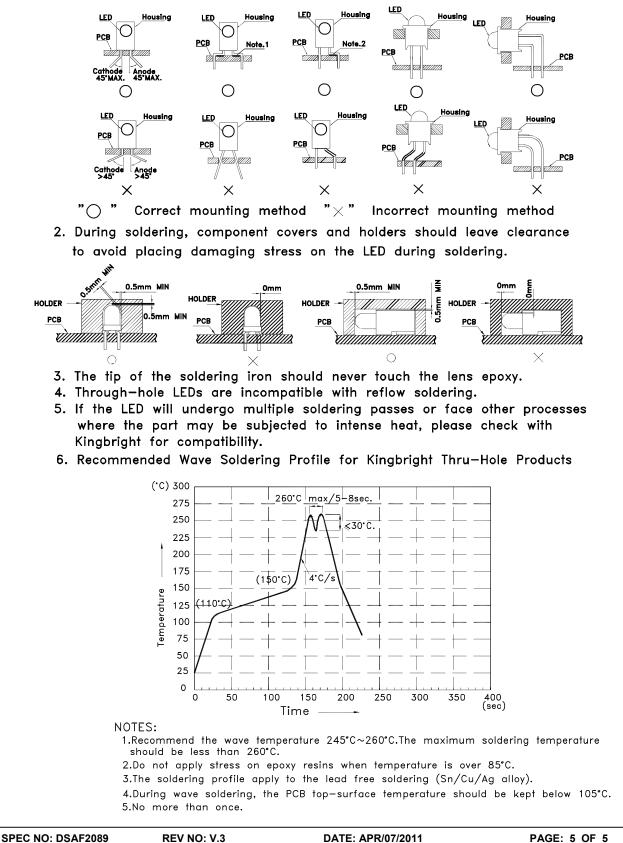
1.1/10 Duty Cycle, 0.1ms Pulse Width.
2.2mm below package base.
3.5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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